

Mrunali Sona

List of Publications by Year in descending order

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Version: 2024-02-01

13
papers

163
citations

1307594

7
h-index

1372567

10
g-index

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all docs

13
docs citations

13
times ranked

196
citing authors

#	ARTICLE	IF	CITATIONS
1	Review on microstructure evolution in Sn–Ag–Cu solders and its effect on mechanical integrity of solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2013, 24, 3149-3169.	2.2	58
2	Individual dispersion of carbon nanotubes in epoxy via a novel dispersion–curing approach using ionic liquids. <i>Physical Chemistry Chemical Physics</i> , 2013, 15, 11696.	2.8	37
3	The effect of reflow time on reactive wetting, evolution of interfacial IMCs and shear strength of eutectic Sn–Cu solder alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2014, 25, 1446-1455.	2.2	17
4	Effect of Reflow Time on Wetting Behavior, Microstructure Evolution, and Joint Strength of Sn-2.5Ag-0.5Cu Solder on Bare and Nickel-Coated Copper Substrates. <i>Journal of Electronic Materials</i> , 2016, 45, 3744-3758.	2.2	12
5	Effects of smear layer removal agents on the physical properties and microstructure of mineral trioxide aggregate cement. <i>Journal of Dentistry</i> , 2017, 66, 32-36.	4.1	11
6	Spreading Behaviour and Joint Reliability of Sn–0.3Ag–0.7Cu Lead-Free Solder Alloy on Nickel Coated Copper Substrate as a Function of Reflow Time. <i>Transactions of the Indian Institute of Metals</i> , 2015, 68, 1027-1031.	1.5	10
7	Evaluation of final irrigation regimens with maleic acid for smear layer removal and wettability of root canal sealer. <i>Acta Odontologica Scandinavica</i> , 2018, 76, 199-203.	1.6	8
8	The Effect of Wetting Gravity Regime on Shear Strength of SAC and Sn-Pb Solder Lap Joints. <i>Journal of Materials Engineering and Performance</i> , 2017, 26, 4177-4187.	2.5	4
9	Wettability and Bond Shear Strength of Sn-9Zn Lead-Free Solder Alloy Reflowed on Copper Substrate. <i>Materials Science Forum</i> , 0, 830-831, 215-218.	0.3	3
10	Assessment of Joint Reliability of Sn–2.5Ag–0.5Cu Solder/Cu as a Function of Reflow Time. <i>Transactions of the Indian Institute of Metals</i> , 2016, 69, 941-947.	1.5	2
11	Effect of Cooling Rate on Joint Shear Strength of Sn-9Zn Lead-Free Solder Alloy Reflowed on Copper Substrate. <i>Materials Performance and Characterization</i> , 2017, 6, 46-54.	0.3	1
12	Wetting Kinetics and Joint Strength of Sn-0.3Ag-0.7Cu Lead-Free Solder Alloy on Copper Substrate as a Function of Reflow Time. <i>Materials Science Forum</i> , 2015, 830-831, 286-289.	0.3	0
13	Wettability, Interfacial Intermetallic Growth and Joint Shear Strength of Eutectic Sn–Cu Solder Reflowed on Bare and Nickel-Coated Copper Substrates. <i>Transactions of the Indian Institute of Metals</i> , 2019, 72, 1579-1583.	1.5	0